L Number			DB	Time stamp
1] 2	2 ("5756380").PN.	USPAT;	2003/04/06 12:
			EPO; JPO;	2003/04/00 12:
			DERWENT;	
2	507		USOCR	
2	597	(insulating adi	USPAT;	2003/04/06 14:
		substrate)	EPO; JPO;	2000/04/00 14.
			DERWENT;	
3	9	madelant attended to	USOCR	
		molded adj insulating adj substrate	USPAT;	2003/04/06 12:
	İ	<i>∤∤</i>	EPO; JPO;	
	Í	- 32	DERWENT;	
4	8	("5102712" L "5172940" L "5000700" L "5 40 40	USOCR	
		\	USPAT	2003/04/06 12:
5	39239	"5719746" "5735040" "5867371" "5962840").PN. (insulative or insulating) adj substrate		
	33233	(modiative of misulating) adj substrate	USPAT;	2003/04/06 12:
			EPO; JPO;	
			DERWENT;	
3	1	((insulative or insulating) adi	USOCR	
		((insulative or insulating) adj substrate) and (charge adj	USPAT;	2003/04/06 13:
		10311)	EPO; JPO;	
	1	•	DERWENT;	"
7	2	("5866952").PN.	USOCR	
	_	(333332).FN.	USPAT;	2003/04/06 12:
			EPO; JPO;	
	1		DERWENT;	
3	10	("4635356" "4783695" "4897153" "5073814"	USOCR	
		"5108825" "5157589" "5161093" "5270371"	USPAT	2003/04/06 12:
		"5300812" "5353498").PN.		
	76	5353498.URPN.		
0 ,	11	("5353498" "5422513" "5455457" "5497033"	USPAT	2003/04/06 12:
ļ	ļ	"5514906" "5527741" "5703400" "5745984"	USPAT	2003/04/06 12:2
ļ		"5895229" "6154366" "6184570").PN.		
11	85	((mold or molded or molding) same (insulating adj		1
		substrate)) and embedded	USPAT;	2003/04/06 12:3
		and an additional and a second	EPO; JPO;	
			DERWENT;	
2	0	(("5756380").PN.) and (charge adj resin)	USOCR	00000000000
	'	, , , (• ge dag 100m)	USPAT; EPO; JPO;	2003/04/06 13:5
			DERWENT;	
	ĺ		USOCR	
13	379	((mold or molded or molding) same (insulating adj	USPAT:	0000000000
		substrate)) and resin	EPO; JPO;	2003/04/06 13:5
	ł		DERWENT;	
			USOCR	
4	2391	(mold or molded or molding) adj substrate	USPAT:	2002/04/00 44.0
	1	• • • • • • • • • • • • • • • • • • • •	EPO; JPO;	2003/04/06 14:0
	1		DERWENT;	
_		<i>"</i>	USOCR	
5	0	((mold or molded or molding) adj substrate) and	USPAT;	2003/04/06 14:0
		(capacitor near embedded)	EPO; JPO;	2000/04/00 14.0
			DERWENT:	
6	4		USOCR	
	47	((mold or molded or molding) adj substrate) and	USPAT;	2003/04/06 14:0
ĺ	1	capacitor	EPO; JPO;	2000/04/00 14.0
1			DERWENT;	
,	46	///madalasa 11 1 1 1 1 1 1 1 1	USOCR	
7	16	(((mold or molded or molding) adj substrate) and	USPAT;	2003/04/06 14:19
		capacitor) and (charge or fill)	EPO; JPO;	
			DERWENT:	
;	229	((mold an mold of the	USOCR	
	229	((mold or molded or molding) adj substrate) and embedded	USPAT;	2003/04/06 14:14
		embedded	EPO; JPO;	
			DERWENT;	
1				

Search History 4/6/03 2:20:05 PM Page 1 C:\APPS\EAST\Workspaces\03-13-03.wsp

19	62	(((mold or molded or molding) adj substrate) and	USPAT:	2003/04/06 14:15
		embedded) and (charge or fill)	EPO; JPO;	2003/04/06 14:15
			DERWENT;	
20	134	(((mold or molded or molding) adj substrate) and embedded) and (charge or chagred or charging or fill or filled or filling)	USOCR USPAT:	2003/04/06 14:16
			EPO; JPO; DERWENT;	
21	84	((((mold or molded or molding) adj substrate) and embedded) and (charge or chagred or charging or fill or filled or filling)) and resin	USOCR	
			USPAT; EPO; JPO;	2003/04/06 14:16
			DERWENT; USOCR	